

MATERIAL DECLARATION SHEET



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|-----------------|---------------------------|-----|---|--|
| Material Number | CM453232 Series (151-102) | | | |
| Product Line | Wound Chip Inductor | | | |
| Compliance Date | 10-17-2010 | | | |
| RoHS Compliant | Yes | MSL | 1 | |

| No. | Construction Element(subpart) | Homogeneous Material | Material weight [g] | Homogeneous Material\ Substances | CASRN if applicable | Materials Mass % | Material Mass % of total unit wt. | Subpart mass of total wt. (%) |
|-----|-------------------------------|----------------------|---------------------|----------------------------------|---------------------|------------------|-----------------------------------|-------------------------------|
| 1 | Ferrite Material | Ferrite | 0.03 | Iron oxide | 1309-37-1 | 63.0 | 17.19 | 27.274 |
| | | | | Nickel oxide | 1313-99-1 | 12.0 | 3.27 | |
| | | | | Zinc oxide | 1314-13-2 | 18.0 | 4.91 | |
| | | | | Copper oxide | 1317-38-0 | 7.0 | 1.91 | |
| 2 | Winding Wire | Copper | 0.015 | Copper | 7440-50-8 | 95.0 | 12.95 | 13.636 |
| | | | | Polyesterimide | 37137-16-1 | 5.0 | 0.68 | |
| 3 | Terminal | Copper | 0.035 | Copper | 7440-50-8 | 95.0 | 30.23 | 31.818 |
| | | | | Tin | 7440-31-5 | 5.0 | 1.59 | |
| 4 | Adhesive | Resin | 0.013 | Epoxy Resin | 25068-38-6 | 65.0 | 7.68 | 11.818 |
| | | | | Dicyanodiamide | 461-58-5 | 6.0 | 0.71 | |
| | | | | Titanium dioxide | 13463-67-7 | 4.0 | 0.47 | |
| | | | | Silicon dioxide | 731-86-9 | 19.0 | 2.25 | |

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|--------------|------------------|--------|-------------|---------------------------|------------|-------|-------|-------|
| 6 | Molding Compound | Silica | 0.005 | Silicon dioxide | 60676-86-0 | 69.0 | 3.14 | 4.545 |
| | | | | Antimony trioxide | 1309-64-4 | 2.5 | 0.11 | |
| | | | | Phenol-formaldehyde resin | 29690-82-2 | 15.0 | 0.68 | |
| | | | | Phenol-Formaldehyde Resin | 9003-35-4 | 10.0 | 0.45 | |
| | | | | Brominated epoxy resin | 40039-93-8 | 2.5 | 0.11 | |
| | | | | Carbon black | 1333-86-4 | 1.0 | 0.05 | |
| 7 | Varnish | Resin | 0.009 | Synthetic resin | 63148-69-6 | 100.0 | 8.182 | 8.182 |
| 8 | Solder | Tin | 0.003 | Tin | 7440-31-5 | 100.0 | 2.73 | 2.727 |
| Total weight | | | 0.11 | | | | | |

This Document was updated on: 2020/12/24

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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- a. "Compliance Date" is not the date supplier submits the MDS, but when the product was first compliant with RoHS.
- b. "This Document was updated on:" is where we indicate when supplier submits the MDS. All previous MDS must be archived for traceability in the future.
- c. Material weights for components less than 100mg (most Semiconductor products) should be listed in milligrams. This avoids all those zeros and round off issues.